



2878

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: V. Vaganov

Group Art Unit: 2878

Serial No.: 09/596,837

Examiner: G. Goudreau

Filed: 06/19/2000

Attorney's Docket

No.: SS-714-01

For:

METHOD FOR FABRICATING MICROSTRUCTURES WITH
DEEP ANISOTROPIC ETCHING OF THICK SILICON WAFERSCOMMISSIONER OF PATENTS
& TRADEMARKS
Washington, D.C. 20231

Date of this Paper:

December 12, 2002RESPONSE TO RESTRICTION REQUIREMENT

In response to the Patent Office Action mailed 11/18/2002, kindly enter the following:

Applicant respectfully traverses the merits of the request. However, applicant elects the isotropic dry etching step claims as indicated in the Office Action (i.e. claims 26, 29-30, 33-34, 48, 51-52, 55, 85, 88, 105, 108 and 115) in the event that no generic claims are finally found allowable.

Respectfully submitted,

Dated: 12/12/2002

By

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Signature of applicant, attorney, or Registered Rep. 12/12/2002
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